	Hit s	Search Text	DBs
29	11	(light\$3 near5 sensitive) or photoresist or resist or	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
30		apparatus or method))) and ((immers\$4 near9 (liquid or fluid or medium)) same ((capillary near9 force) or capillarits3 or	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit s	Search Text	DBs
31		(light\$3 near5 sensitive) or photoresist or resist or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
33	11	((immersion near14 lithography) or ((liquid or fluid) near9 immersion near14 (system or apparatus or method))) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive)) and ((immers\$4 near9 (liquid or fluid)) same ((capillary near9 force) or capillarit\$3 or capillary) same (contact\$4 or prevent\$4 or flatten\$4 or area or pressure) same (workpiece or substrate or target or wafer))	US-PGPUB

	Hit s	Search Text	DBs
34	41	apparatus or method))) and ((immers\$4 near9 (liquid or fluid or medium)) same ((capillary	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
35	0	355/77.ccls. and ((immersion near14 lithography) or (liquid near9 immersion)) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive)) and ((substrate or wafer or workpiece) same (immersi\$3 near6 (fluid\$4 or liquid or medium)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hit	Search Text	DBs
36	0	((substrate or wafer or workpiece) same (immersi\$3 near6 (fluid\$4 or liquid or medium))) and (modulat\$4 or (spatial near14	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
37	0	355/77.ccls. and ((immersion near14 lithography) or (liquid near9 immersion)) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive)) and ((substrate or wafer or workpiece) same (immersi\$3 near6 (fluid\$4 or liquid or medium))) and (modulat\$4 or (spatial near14	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit	Search Text	DBs
	s	Search Text	DBS
38	0	((substrate or wafer or workpiece) same (immersi\$3 near6 (fluid\$4 or liquid or medium))) and (modulat\$4 or (spatial near14	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
39	0	355/53.ccls. and ((immersion near14 lithography) or (liquid near9 immersion)) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive)) and ((substrate or wafer or workpiece) same (immersi\$3 near6 (fluid\$4 or liquid or medium))) and (modulat\$4 or (spatial near14	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit	Search Text	DBs
	s		
40	0	<pre>workpiece) same (immersi\$3 near6 (fluid\$4 or liquid or medium)))</pre>	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
41	1	355/18.ccls. and ((immersion near14 lithography) or (liquid near9 immersion)) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive)) and ((substrate or wafer or workpiece) same (immersi\$3 near6	DERWENT; IBM_TDB